Freescale Semiconductor Inc

PART INFORMATION	
Mfg Item Number	MPXHZ6250A6U
Mfg Item Name	SNSR SSOP 08 W/O PORT

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2014-11-04
Response Document ID	0886K50010S204A1.22
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	No
HalogenFree	No
Plating Indicator	e4
EU RoHS Exemption(s)	7c-I

MANUFACTURING	
Mfg Item Number	MPXHZ6250A6U
Mfg Item Name	SNSR SSOP 08 W/O PORT
Version	ALL
Weight	0.374700
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	250 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Gel Die Encapsulant	0.0133						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.009975	g	750000	75		26621	2.6621
Gel Die Encapsulant		Solvents, additives, and other materials	Plastics: Perfluoropropylether polymer	-		0.003325	g	250000	25		8873	0.8873
Gel Die Encapsulant	0.0133						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.01064	g	800000	80		28396	2.8396
Gel Die Encapsulant		Solvents, additives, and other materials	Plastics: Perfluoropropylether polymer	-		0.00266	g	200000	20		7099	0.7099
Cap/Cover	0.0809						g					
Cap/Cover		Metals	Chromium, metal	7440-47-3		0.01457947	g	180216	18.0216		38909	3.8909
Cap/Cover		Solvents, additives, and other materials	Sulfur	7704-34-9		0.00002427	g	300	0.03		64	0.0064
Cap/Cover		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.00003236	g	400	0.04		86	0.0086
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-3		0.00060748	g	7509	0.7509		1621	0.1621
Cap/Cover		Metals	Iron, metal	7439-89-6		0.06484645	g	801563	80.1563		173062	17.3062
Cap/Cover		Metals	Manganese, metal	7439-96-5		0.00080997	g	10012	1.0012		2161	0.2161
Non-Conductive Epoxy/Adhesive	0.0006						g					
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silicone gum	67762-94-1		0.00000619	g	10324	1.0324		16	0.0016
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and Silicones, di-Me, Me vinyl, vinyl group-terminated	68083-18-1		0.00007375	g	122911	12.2911		196	0.0196
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.00023599	g	393313	39.3313		629	0.0629
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-		0.00013274	g	221239	22.1239		354	0.0354
Non-Conductive Epoxy/Adhesive		Glass	D4 and HMDZ treated Silicon Dioxide	68937-51-9		0.0000885	g	147493	14.7493		236	0.0236
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.00005605	g	93412	9.3412		149	0.0149
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7		0.00000678	g	11308	1.1308		18	0.0018
Copper Lead Frame	0.2529						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.21364688	g	844788	84.4788		570196	57.0196
Copper Lead Frame		Metals	Gold, metal	7440-57-5		0.00016894	g	668	0.0668		450	0.045
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.00032599	g	1289	0.1289		870	0.087
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.00487515	g	19277	1.9277		13010	1.301
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.00237094	g	9375	0.9375		6327	0.6327
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.00011608	g	459	0.0459		309	0.0309
Copper Lead Frame		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.00977737	g	38661	3.8661		26093	2.6093
Copper Lead Frame		Glass	Fibrous-glass-wool	65997-17-3		0.02118417	g	83765	8.3765		56536	5.6536
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.00043448	g	1718	0.1718		1159	0.1159
Pb Glass Frit Semiconductor Di	0.0131				7c-I		g					
Pb Glass Frit Semiconductor Di		Lead/Lead Compounds	Lead (II) titanate	12060-00-3		0.00013599	g	10381	1.0381		362	0.0362
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.00013025	g	9943	0.9943		347	0.0347
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.00013025	g	9943	0.9943		347	0.0347
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-		0.01270351	g	969733	96.9733		33903	3.3903
Bonding Wire	0.0006						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0006	g	1000000	100		1601	0.1601

LINKS	
MCD LINK	
Freescale website	http://www.freescale.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf
China RoHS	http://www.freescale.com/chinarohs
REACH signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf
ELV signed letter	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf
Conflict Minerals statement	http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf
FREESCALE ENVIRONMENTAL INFORMATION	
EPP website	http://www.freescale.com/epp
FAQ	http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ
Technical Service Request	https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPXHZ6250A6U_IPC1752_v11.xml

http://www.freescale.com/mcds/MPXHZ6250A6U_IPC1752A.xml